

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

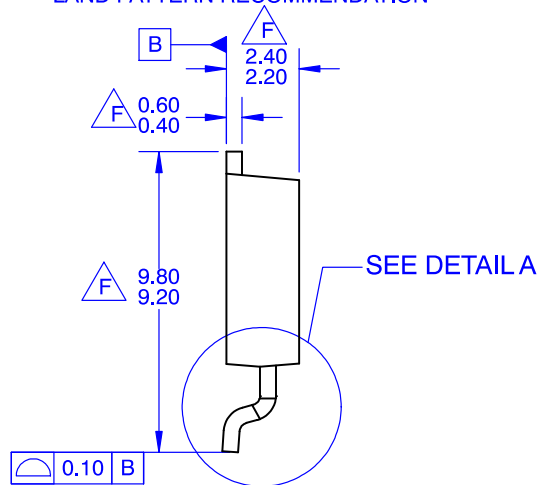
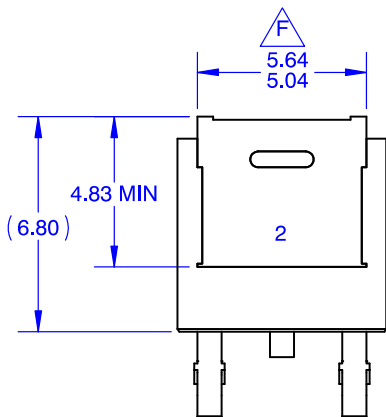
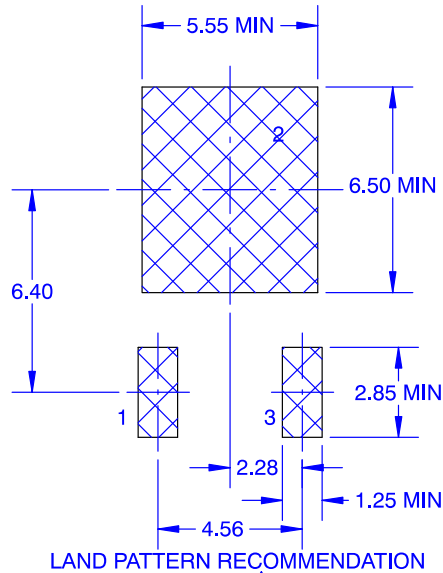
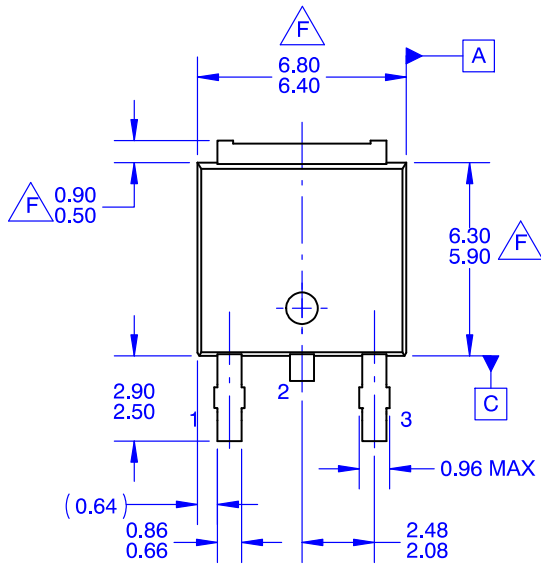


### DPAK3

#### CASE 369AK

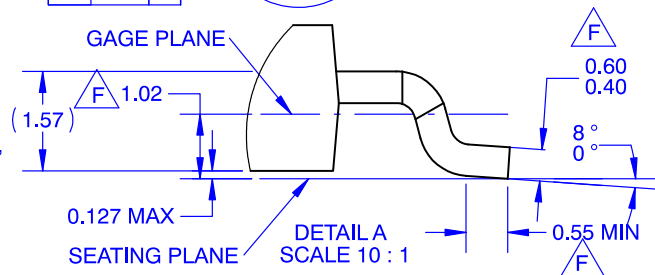
#### ISSUE O

DATE 30 SEP 2016



**NOTES: UNLESS OTHERWISE SPECIFIED**

- A) NOT COMPLIANT TO JEDEC TO-252 VARIATION AB
- B) ALL DIMENSION ARE IN MILLIMETER
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D) LAND PATTERN PER IPC7351A STANDARD TO228P991X239-3N
- E) DOES NOT COMPLY TO JEDEC STANDARD VALUE.



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